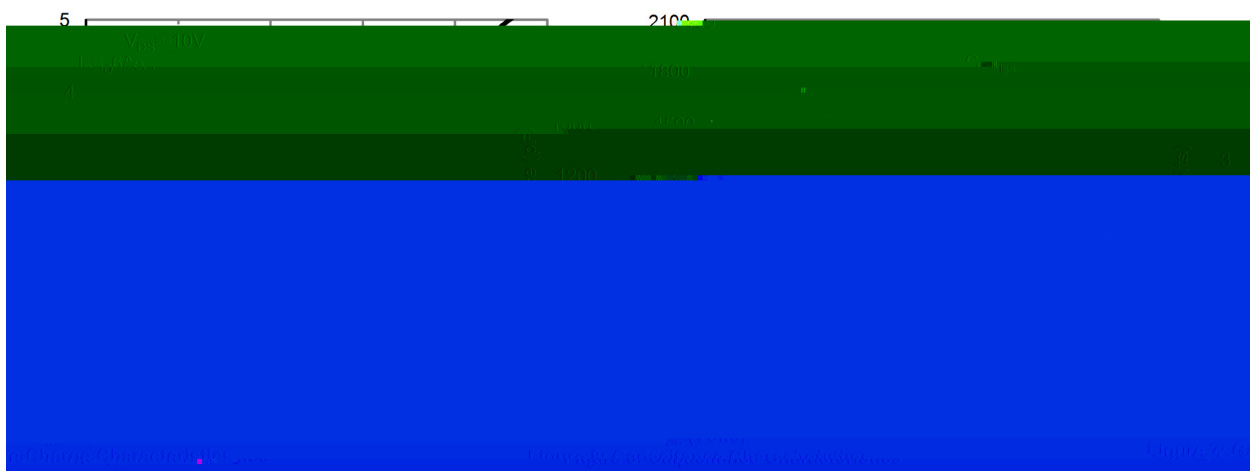
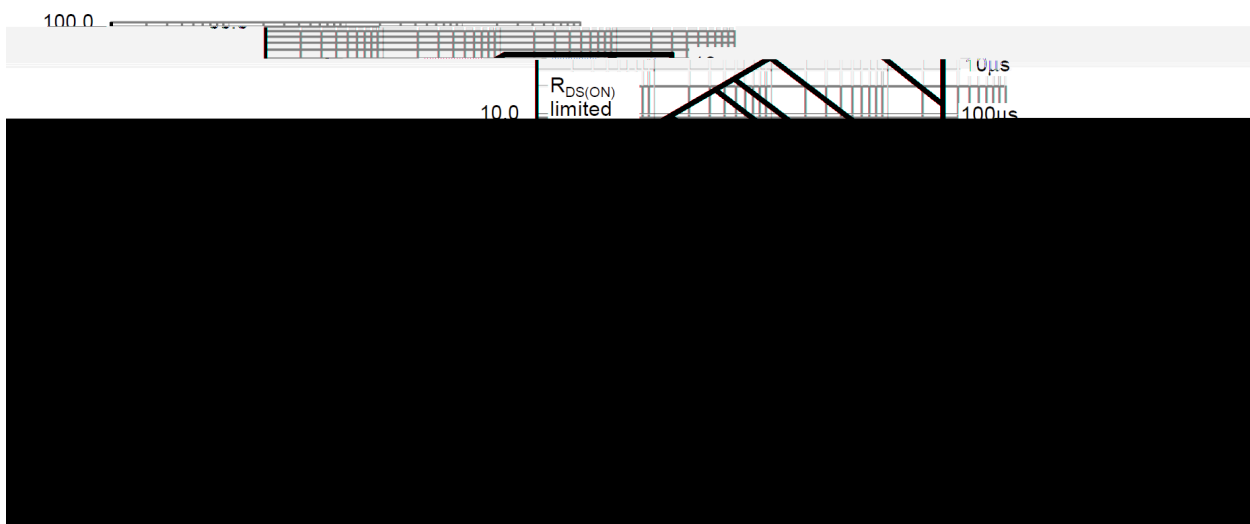
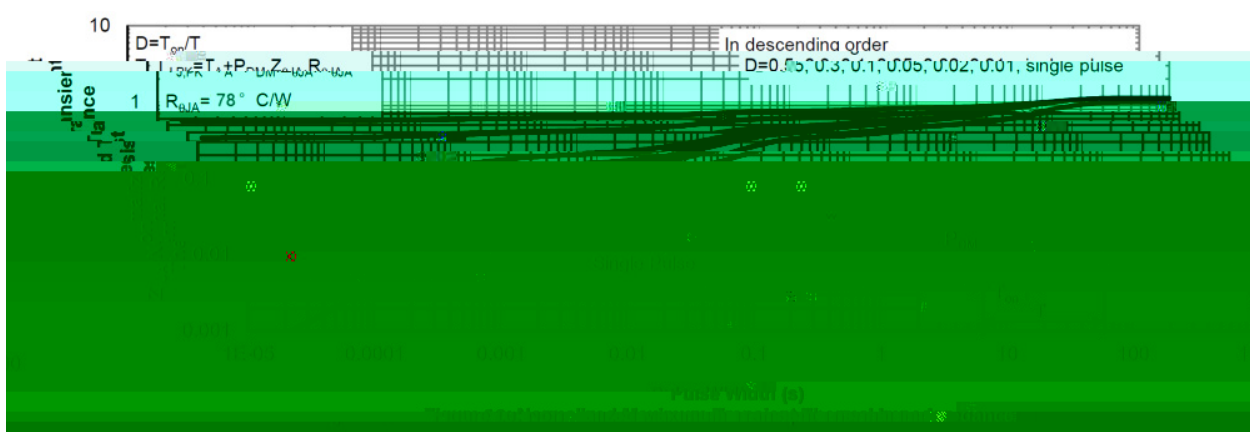


Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	-20	V
Gate-Source Voltage		V_{GSS}	± 12	V
Continuous Drain Current		$I_D (T_a=25^\circ\text{C})$	-9.5	A
Pulsed Drain Current		I_{DM}	-43	A
Power Dissipation for Single Operation		$P_D (T_a=25^\circ\text{C})$	2.8	W
Maximum Junction Temperature		T_j	150	
Storage Temperature Range		T_{stg}	$-55 \sim 150$	
Thermal Resistance-Junction to Ambient	$t \sim 10\text{s}$	$R_{\theta JA}$	45	/W
	Steady State		78	/W

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D = -250\mu A$ $V_{GS} = 0V$	-20	-22.5		V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20V$ $V_{GS} = 0V$			-1.0	μA
Gate-Body leakage current	I_{GSS}	$V_{DS} = 0V$ $V_{GS} = \pm 12V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ $I_D = -250\mu A$	-0.5	-0.6	-1.0	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = -4.5V$ $I_D = -5A$		20	22	m Ω
		$V_{GS} = -2.5V$ $I_D = -4A$		26	30	
		$V_{GS} = -1.8V$ $I_D = -3A$		35	100	
Diode Forward Voltage	V_{SD}	$I_S = -1A$ $V_{GS} = 0V$			-1.2	V
Gate resistance	R_g	$V_{GS} = 0V$, $f = 1MHz$ $V_{DS} = 0V$,		11		Ω
Input Capacitance	C_{iss}	$V_{GS} = 0V$ $V_{DS} = -5V$ $f = 1MHz$		1700		pF
Output Capacitance	C_{oss}			600		
Reverse Transfer Capacitance	C_{rss}			450		
Total Gate Charge	Q_g	$V_{GS} = -4.5V$, $I_D = -6A$ $V_{DS} = -10V$,		13		nC
Gate Source Charge	Q_{gs}			2.5		
Gate Drain Charge	Q_{gd}			4.2		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = -4.5V$ $R_L = 1.25\Omega$ $V_{DS} = -10V$ $R_{GEN} = 3\Omega$		7.5		ns
Turn-On Rise Time	t_r			29.2		
Turn-Off Delay Time	$t_{d(off)}$			103		
Turn-Off Fall Time	t_f			50		

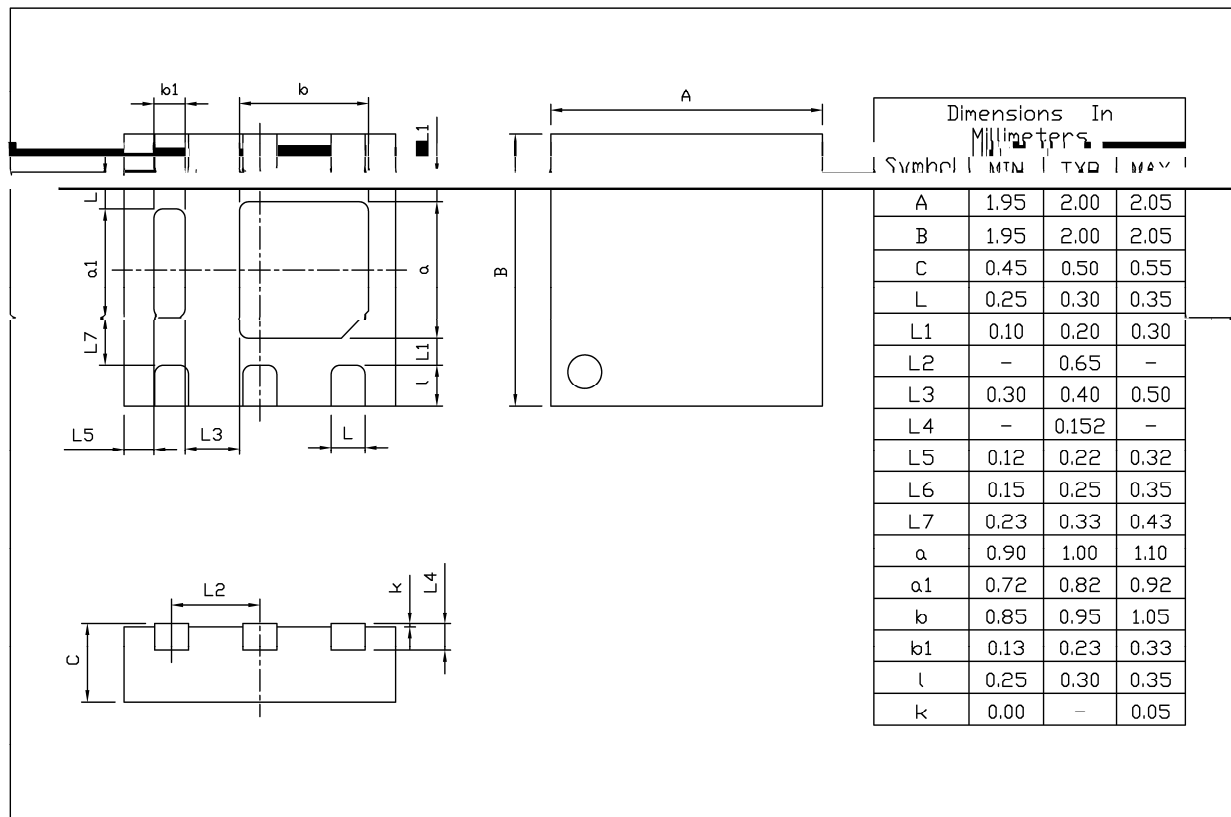


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DFN2 ×2B-6L-0.5

Unit:mm



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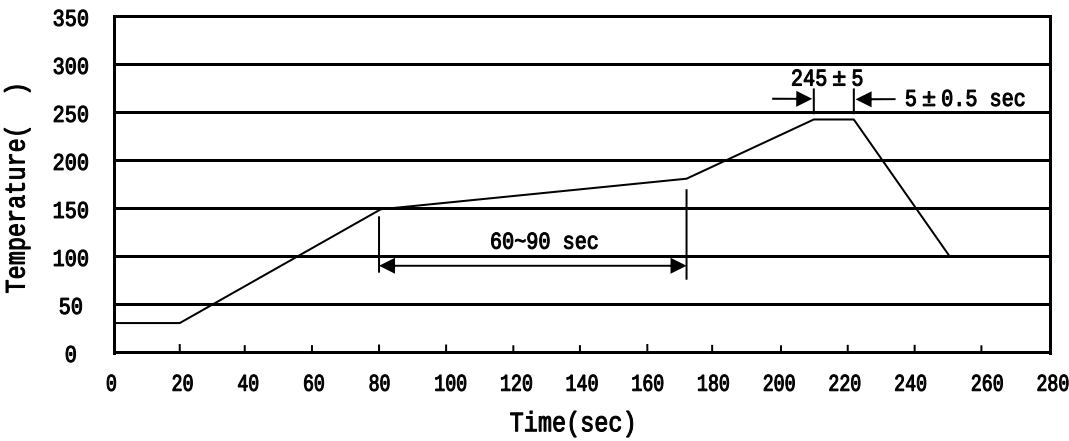
$$\mathbb{H} \cdot f \check{h}^N \mathbb{P} \quad \mathbb{I} \cdot f \check{h}^N \Psi \mathbb{P}$$

Company Code

Product Type Code

Lot No. Code, code change with Lot No

Temperature Profile for IR Reflow Soldering(Pb-Free)



注意

1. 预加热: 150~180 °C , Time: 60~90sec;
2. 峰值温度: 245 ± 5 °C , Duration: 5 ± 0.5sec;
3. 冷却速度: 2~10 °C /sec.

Note:

- 1.Preheating:150~180 °C , Time:60~90sec.
- 2.Peak Temp.:245 °C , Duration:5 ± 0.5sec.
3. Cooling Speed: 2~10 °C /sec.

峰值温度: 260 ± 5 °C 持续时间: 10 ± 1 sec. Temp.:260±5 Time:10±1 sec

包装形式 / REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
DFN2×2B-6L	4,000	10	40,000	4	160,000	7 ×8	210×205×205	445×435×230